

AMENDMENTS TO THE CLAIMS:

1. (Currently Amended) A light emitting apparatus, comprising:

a semiconductor light emitting element that radiates light from ~~[[its]]~~ a light emission surface provided on a side ~~[[the]]~~ opposite ~~side to its~~ to an electrode forming surface of said light emitting element;

lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;

a transparent structure that is optically connected with the light emission surface and has a light distribution characteristic based on its three-dimensional shape, said transparent structure being mounted on a substrate positioned on a side opposite said light emitting element; and

light transmitting resin that seals the semiconductor light emitting element and the transparent structure.

2. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a length in the horizontal direction greater than that of the semiconductor light emitting element.

3. (Original) The light emitting apparatus according to claim 1, wherein:

the transparent structure has a thickness of half that of the semiconductor light emitting element to twice the length of a shorter side of the semiconductor light emitting element.

4. (Original) The light emitting apparatus according to claim 1, wherein:
the transparent structure has a microscopic uneven surface to diffuse light.
5. (Original) The light emitting apparatus according to claim 1, wherein:
the transparent structure has a reflection layer formed on its surface.
6. (Original) The light emitting apparatus according to claim 1, wherein:
one of the lead frames has a cup portion, and
the transparent structure is fixed on the cup portion through adhesive resin with light diffusion material mixed therein.
7. (Original) The light emitting apparatus according to claim 1, wherein:
the electrodes do not transmit light.
8. (Currently Amended) A light emitting apparatus, comprising:
a semiconductor light emitting element that radiates light from ~~[[its]]~~ a light emission surface provided on a substrate ~~[[the]]~~ opposite ~~side to its~~ an electrode forming surface;
lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;
a transparent structure that is optically connected with the light emission surface and has a light distribution characteristic based on its three-dimensional shape; and

light transmitting resin that seals the semiconductor light emitting element and the transparent structure, the light transmitting resin including a phosphor to wavelength-convert light emitted from the semiconductor light emitting element.

9. (Original) The light emitting apparatus according to claim 8, wherein:
the light transmitting resin contains two or more kinds of phosphors.
10. (New) The light emitting apparatus according to claim 1, wherein the semiconductor light emitting element comprises the substrate, a buffer layer, an n-type semiconductor layer, a light-emitting layer, and a p-type semiconductor layer.
11. (New) The light emitting apparatus according to claim 1, wherein the semiconductor light emitting element comprises a gallium nitride system compound semiconductor.
12. (New) The light emitting apparatus according to claim 1, wherein the transparent structure comprises a light transmitting material comprising at least one of SiO₂, Al₂O₃, SiC, Si₃N₄, AlN, ZrO₂, borosilicate glass, and alumino-silicate glass.
13. (New) The light emitting apparatus according to claim 1, wherein the substrate comprises sapphire.

14. (New) The light emitting apparatus according to claim 1, wherein the transparent structure is connected to the light emission surface by an adhesive layer.
15. (New) The light emitting apparatus according to claim 14, wherein the adhesive layer comprises a transparent adhesive.
16. (New) A light emitting apparatus, comprising:
- a semiconductor light emitting element that radiates light from a light emission surface provided on an opposite side to an electrode forming surface of said light emitting element;
 - lead frames that are electrically connected to electrodes formed on the electrode forming surface through wires;
 - a transparent structure that is optically connected with the light emission surface and has a light distribution characteristic based on its three-dimensional shape; and
 - light transmitting resin that seals the semiconductor light emitting element and the transparent structure,
- wherein the transparent structure has a length in the horizontal direction greater than that of the semiconductor light emitting element.